MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

SOIC8
CASE 751DZ
ISSUE 0

DATE 30 SEP 2016

NOTES:
A) NO STANDARD APPLIES TO THIS PACKAGE
B) ALL DIMENSIONS ARE IN MILLIMETERS.
C) DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS.
D) LANDPATTERN STANDARD: SOIC127P600X175-8M.

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